

United States Patent [19]

Nakashiba et al.

[11] Patent Number: 5,762,539**[45] Date of Patent:** Jun. 9, 1998**[54] APPARATUS FOR AND METHOD FOR POLISHING WORKPIECE**

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[58] Field of Search 451/41, 285-289, 451/388, 53, 5

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[57] ABSTRACT

A polishing apparatus for polishing a workpiece such as a semiconductor wafer has a turntable with a polishing surface, and a top ring for holding a workpiece and pressing the workpiece against the polishing surface under a first pressing. The polishing apparatus has a pressurized fluid source for supplying pressurized fluid, and a plurality of openings provided in the holding surface of the top ring for ejecting the pressurized fluid supplied from the pressurized fluid source. A plurality of areas each having the openings are defined on the holding surface so that the pressurized fluid is selectively ejectable from the openings in the respective areas.

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11 Claims, 9 Drawing Sheets

